


MANUFACTURE OF THIN TEMPERATURE FUSE

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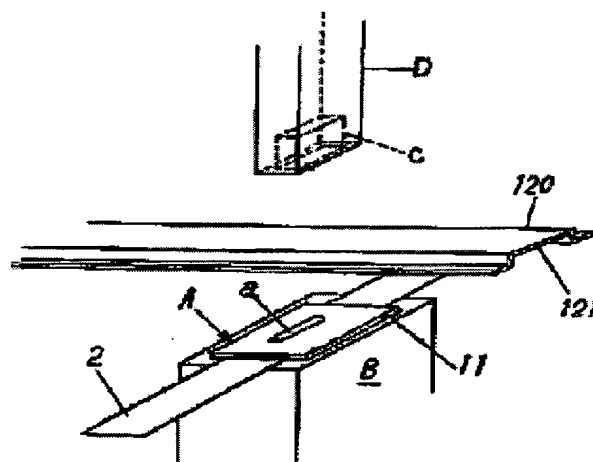
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Abstract of JP2000113784

PROBLEM TO BE SOLVED: To provide a fuse easily having good sealing ability by fusing a resin cover film with a periphery surrounding a fusible alloy piece with flux coating low melting point of a resin base film, and sealing this fusible alloy piece with low melting point alloy.

SOLUTION: A long resin cover film 120 extending orthogonally to the longitudinal direction of a lead conductor 2 of a temperature fuse body A is placed on a resin base film 11, and positioning of the cover film 120 in relation to the longitudinal direction is performed by a positioning jig. A heating die D having a recessed part (c) for accommodating a fusible alloy piece (a) with flux coating low melting point is dropped, the cover film 120 is thermally fused with a periphery surrounding the fusible alloy piece (a) with flux coating low melting point on the base film 11. The heating die D is provided with a Thomson blade for cutting the cover film 120 at the both edges of the width of the base film 11, and the blade cuts the cover film 120 at thermally fusing time.



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